

PTFE/Woven Fiberglass/Ceramic Filled Laminate For Microwave Printed Circuit Boards

AD1000 is a high dielectric constant substrate that permits circuit miniaturization, compared to traditional low loss materials. It is especially beneficial for power amplifiers, filters, couplers and other components using low impedance lines.

AD1000 is a woven glass reinforced laminate. This allows for Greater Dimensional Stability and Mechanical Robustness than other 10 Dk Products. Its large panel size is also advantageous for "multi-circuits per panel" processing.

AD1000 is considered a "soft substrate" and is relatively insensitive to vibrational stress. This allows miniaturized circuitry without requiring the complicated processing or special handling associated with brittle pure ceramic or ceramic hydrocarbon materials.

AD1000 is compatible with processing used for standard PTFE based printed circuit board substrates. In addition, the low Z-axis thermal expansion provided by the ceramic loading will improve plated through hole reliability, compared to typical PTFE based laminates. The low X-Y thermal expansion provides excellent matching to ceramic chip carriers and other ceramic components.

AD1000 was specifically developed for Miniaturized Circuitry for compact devices (i.e., GPS Receivers), Patch Antennas (where smaller size is required), Satellite Communications Systems, Power Amplifiers (PAs), Low Noise Amplifiers (LNAs), Low Noise Block Downconverters (LNBs), Radar Modules and Manifolds, Aircraft Collision Avoidance Systems (TCAS), and Ground Based Radar Systems.

Features:

- Only Woven Glass Reinforced PTFE/ Ceramic with Dk of 10.2 or greater
- Thermal Conductivity is "Best-in-Class"
- High copper peel strength allows for thinner etched line widths
- Lowest Insertion Loss Available
- Larger Panel Sizes Available
- Low Moisture Absorption
- Excellent CTE Values lead to highly reliability ceramic component attachment and PTH reliability

Benefits:

- Mechanically Robust
- Greater Dimensional Stability than Other 10 Dk Products
- Circuit Miniaturization Leads to Weight Savings
- Heat Dissipation and Management
- Greater Signal Integrity
- Cost-Effective Board Layout and Board Processing
- Low Loss in Humid Environments

Typical Applications:

- Ideal for X-Band and Below
- Radar Modules and Manifolds
- Aircraft Collision Avoidance Systems (TCAS)
- Ground Based Radar Surveillance Systems
- Miniaturized Circuitry & Patch Antennas
- Power Amplifiers (PAs)
- Low Noise Amplifiers (LNAs)



Burnett	Hales	Value	Took Marked		
Property ————————————————————————————————————	Units	Value	Test Method		
1. Electrical Properties					
Dielectric Constant (may vary by thickness)					
@1 MHz	-		IPC TM-650 2.5.5.3		
@ 10 GHz	-	10.20	IPC TM-650 2.5.5.5		
Dissipation Factor					
@ 1 MHz	-		IPC TM-650 2.5.5.3		
@ 10 GHz	-	0.0023	IPC TM-650 2.5.5.5		
Temperature Coefficient of Dielectric	-				
TCεr @ 10 GHz (-40-150°C)	ppm/°C	-380	IPC TM-650 2.5.5.5		
Volume Resistivity			150 511 555 5 5 5		
C96/35/90	MΩ-cm	1.40x10 ⁹	IPC TM-650 2.5.17.1		
E24/125	MΩ-cm	5.36x10 ⁷	IPC TM-650 2.5.17.1		
Surface Resistivity					
C96/35/90	ΜΩ	1.80x10 ⁹	IPC TM-650 2.5.17.1		
E24/125	MΩ	3.16x10 ⁸	IPC TM-650 2.5.17.1		
Electrical Strength	Volts/mil (kV/mm)	622 (24.5)	IPC TM-650 2.5.6.2		
Dielectric Breakdown	kV	>45	IPC TM-650 2.5.6		
Arc Resistance	sec	>180	IPC TM-650 2.5.1		
2. Thermal Properties					
Decomposition Temperature (Td)					
Initial	°C	>500	IPC TM-650 2.3.41		
5%	°C	>500	IPC TM-650 2.3.41		
T260	min	>60	IPC TM-650 2.4.24.1		
T288	min	>60	IPC TM-650 2.4.24.1		
T300	min	>60	IPC TM-650 2.4.24.1		
Thermal Expansion, CTE (x,y) 50-150°C	ppm/°C	8, 10	IPC TM-650 2.4.41		
Thermal Expansion, CTE (z) 50-150°C	ppm/°C	20	IPC TM-650 2.4.24		
% z-axis Expansion (50-260°C)	%		IPC TM-650 2.4.24		
3. Mechanical Properties					
Peel Strength to Copper (1 oz/35 micron)					
After Thermal Stress	lb/in (N/mm)	>12 (2.1)	IPC TM-650 2.4.8		
At Elevated Temperatures (150°)	lb/in (N/mm)	13.6 (2.4)	IPC TM-650 2.4.8.2		
After Process Solutions	lb/in (N/mm)		IPC TM-650 2.4.8		
Young's Modulus	kpsi (MPa)		IPC TM-650 2.4.18.3		
Flexural Strength (Machine/Cross)	kpsi (MPa)		IPC TM-650 2.4.4		
Tensile Strength (Machine/Cross)	kpsi (MPa)	5.1/4.3 (35/30)	IPC TM-650 2.4.18.3		
Compressive Modulus	kpsi (MPa)	>425	ASTM D-3410		
Poisson's Ratio	-	\	ASTM D-3039		
4. Physical Properties					
Water Absorption	%	0.03	IPC TM-650 2.6.2.1		
Density, ambient 23°C	g/cm³	3.20	ASTM D792 Method A		
Thermal Conductivity	W/mK	0.81	ASTM E1461		
Flammability	class	Meets V0	UL-94		
NASA Outgassing, 125°C, ≤10 ⁻⁶ torr	%		NASA SP-R-0022A		
Total Mass Loss	%	0.01	NASA SP-R-0022A		
Collected Volatiles	%	0.00	NASA SP-R-0022A		
Water Vapor Recovered	%	0.00	NASA SP-R-0022A		

^{**}Alternative Thickness and Dielectric Constant (Dk) options are available. Tighter tolerances are also available under the AD1001 designation for some thickness. Please discuss your needs with Arlon's Applications Engineering Teams.

Thickness and Dielectric Constant Alternatives

Thickness	0.006	0.0105	0.015	0.020	0.025	0.030	0.050	0.059	0.125	0.127
(mils)	±0.0005	±0.0010	±0.0015	±0.002	±0.002	±0.002	±0.002	±0.003	±0.003	±0.003
Dielectric	7.8	9.1	9.7	10	10.2	10.35	10.2 or 10.6	10.7	10.2	10.9
Constant	±0.30	±0.35	±0.35	±0.35	±0.35	±0.35	±0.35	±0.35	±0.35	±0.35

^{*} Thicker Options are available. Please Contact Customer Service or your Local Arlon

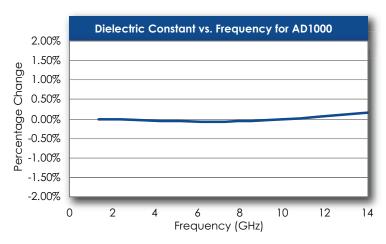


Figure 1
Demonstrates the Stability of Dielectric Constant across
Frequency. This information was correlated from data
generated by using a free space and circular resonator
cavity. This characteristic demonstrates the inherent
robustness of Arlon Laminates across Frequency, thus
simplifying the final design process when working across
EM spectrum. The stability of the Dielectric Constant of
AD1000 over frequency ensures easy design transition and
scalability of design.

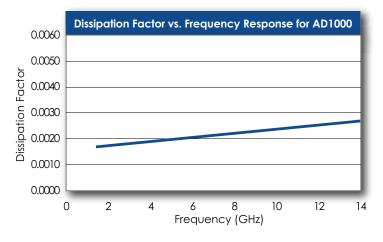


Figure 2
Demonstrates the Stability of Dissipation Factor across
Frequency. This characteristic demonstrates the inherent
robustness of Arlon Laminates across Frequency, providing a
stable platform for high frequency applications where signal
integrity is critical to the overall performance of the application.

Material Availability:

AD1000 laminates are available in a range of thicknesses from 0.020" to 0.127" (and beyond). AD1000 is supplied with 1/2, 1 or 2 ounce standard or reverse treat electrodeposited (ED) copper on both sides. Other copper weights and rolled copper foil are available. AD1000 is available bonded to heavy metal ground planes. Aluminum, brass or copper plates also provide an integral heat sink and mechanical support to the substrate.

Other combinations of thickness and cladding may be available. Contact Arlon with any requests for nonstandard materials. When ordering AD1000, please specify thickness, cladding, panel size, and any other special considerations. Standard panel sizes include: 18" x 24", 12" x 18" and 16" x 18". Contact Arlon Customer Service for other panel sizes.



Arlon Microwave Materials... Challenge Us

For samples, technical assistance, customer service or for more information, please contact Arlon Materials for Electronics Division at the following locations:

NORTH AMERICA:

Arlon, Inc.

Electronic Substrates 9433 Hyssop Drive

Rancho Cucamonga, CA 91730

Tel: (909) 987-9533 Fax: (909) 987-8541

Arlon, Inc.

Microwave Materials 1100 Governor Lea Road

Bear, DE 19701 Tel: (800) 635-9333

Outside U.S. & Canada: (302) 834-2100

Fax: (302) 834-2574

NORTHERN EUROPE:

Arlon, Inc. 44 Wilby Avenue Little Lever Bolton, Lancashire BL31QE United Kingdom

Tel: (44) 120-457-6068 Fax: (44) 120-479-6463

SOUTHERN CHINA:

Arlon, Inc.
Room 601, Unit 1, Bldg 6
Liyuan, Xincun Shahe
Shenzhen, China 518053

Tel: (86) 755-269-066-12 Fax: (86) 755-26910475

NORTHERN CHINA:

Arlon, Inc. Room 11/401, No. 8 Hong Gu Road Shanghai, China 200336 Tel/Fax: (86) 21-6209-0202

SOUTHERN EUROPE:

Arlon, Inc.

1 Bis Rue de la Remarde 91530 Saint Cheron, France

Tel: (33) 951-096-082 Fax: (33) 164-566-489

> Certified to ISO 9001:2008